



# Features

- Disciplines to a 1PPS input
- Compact form factor for a wide range of applications
- Wide temperature spectrum performance

# **Benefits**

• Low power operation

# **Applications**

- Delivers GSM and UMTS level stability in free run (without need for recalibration)
- Ideal performance levels for CDMA networks
- Stratum 2, or Type II level performance for synchronization for central offices/ network nodes

The Microsemi innovative rubidium atomic oscillator, the SA.22c, is the culmination of significant advances in physics miniaturization and integration. The SA.22c's compact form factor, low power consumption, and full-spectrum temperature operation make rubidium performance accessible to a wide range of synchronization applications, from telecom networks to handheld test and measurement devices.

The SA.22c is a board mounted rubidium oscillator with a complete range of output frequencies available to meet the needs of a large set of synchronization applications. The SA.22c can be disciplined to a precision 1PPS reference input (such as GPS) or it can operate by itself as a precision stand-alone reference. The SA.22c's outputs also include a 1PPS.

The SA.22c can communicate through its serial port to provide dynamic frequency control and selection and to enable or disable outputs. The SA.22c can be queried for information such as serial number, operating hours, operating temperature, event history, self-test, and other such performance indicators.

The SA.22c provides highly precise outputs using the inherent stability of the rubidium atom, in a compact form factor. This delivers an excellent value to the market for a wide range of applications.



# SA.22c Precision Rubidium Oscillator

Electrical Specifications					
Frequency Outputs*					
Output 1	Derived square wave at 1.544, 2.048, 5, 9.8304, 10, 10.24, 10.29, 13, or 15 MHz (5 V ACMOS)				
Output 2	1 PPS				
Phase Noise (@10 M	Hz)				
1 Hz	<-72 dBc/Hz				
10 Hz	<-90 dBc/Hz				
100 Hz	<–128 dBc/Hz				
1 kHz	<-140 dBc/Hz				
10 kHz	<–148 dBc/Hz				
Stability (Allan Devia	tion)				
t=1 second	<3E-11				
t=10 second	<1E-11				
t=100 second	<3E-12				
Control Range					
With digital input	±1E-6 with granularity of 1E-12				
With analog input	$\pm$ 1.5E-9, 0-5 V into 5 kΩ or optional $\pm$ 6.5E-9, 0-5 V into 5 kΩ				
1PPS Output					
Pulse width	400 ns				
Amplitude	VL<0.5 V, VH >4.5 V, 15 pf load				
Rise time	10 ns, 15pf load				
Warm-up Time					
Time to lock	5 mins (accuracy at lock <5E-8)				
Time to <1E-9 @ 25 °C	7.5 minutes				
Power Consumption					
Warm-up	18.5 W maximum (–10 °C to +75 °C)				
Operating	15 W @ –10 °C, 10 W @ 25 °C, 5 W @ 75 °C baseplate				
Voltage Coefficient					
+5 Vdc ±5%	Magnitude (df/f) <2E-11 peak to peak				
+15 Vdc ±5%	Magnitude (df/f) <3E-11peak to peak				
Frequency Characteristics					
Jitter	<10 ps RMS				
Accuracy at shipment	<±5E-11 (25 °C), typical				
Retrace	<±2E-11 (on-off-on: 24 h, 48 h, 12 h @ 25 °C)				
Supply Voltage/Curre	Supply Voltage/Current (both required)				
+5 Vdc ±5%	Maximum current <100 mA				
+15 Vdc ±5%	Maximum current <1.2 A				
Health Monitoring					
ACMOS	Service (J1-12) & Lock (J1-14) status				
Serial	KS-232 (J1-13 & 16)				

Application Profiles					
Profile	Monthly Aging Rate dF/F	Tempco	Temperature Range		
AP1 <sup>1</sup>	±4E-11	<1E-10	–10 °C to 75 °C		
AP2 <sup>2</sup>	±5E-11	<3E-10	0 °C to 50 °C		
AP2A <sup>3</sup>	±3E-10	<2E-10	–10 °C to 75 °C		
AP3 <sup>4</sup>	±3E-10	<3E-9	–10 °C to 75 °C		

 High performance applications

 <sup>2</sup> Tempco of Microsemi LPRO/XPRO

 <sup>3</sup> Ideal for CDMA holdover

 <sup>4</sup> GSM/UMTS specifications (<5E-8 over 20 yrs)</td>

Environmental Specifications					
Radiated emissions	Compliant to FCC part 15, Class B				
Operating					
Temperature	-10 °C to +75 °C baseplate				
Magnetic field sensitivity	$<\pm 6E-11/Gauss$ (up to $\pm 2$ Gauss)				
Humidity	GR-63-CORE, Issue 4, April 2012, section 4.1.2: 5-85% RH, operating				
Vibration	GR-63-CORE, Issue 4, April 2012, section 4.4.4 & 5.4.2 Opt2: Random Vibration 0.15 grms, unit locked				
Storage and Transport					
Temperature	–55 °C to +100 °C				
Shock/vibration	GR-63-CORE, Issue 4, April 2012; section 4.4.5 & 5.4.3: Random Vibration 0.78 grms, section 4.3.1 & 5.3.1.1:Packaged Drop from 1000 mm				

Physical Specifications				
Weight	< 428.5gm (<15 oz )			
Size	23.6 mm H x 78.3 mm W x 112.4 mm L (0.93" H x 3.08" W x 4.43 L)			
Volume	207.70 cm <sup>3</sup> (12.7 in <sup>3</sup> )			

\*Contact the manufacturer for information about other frequency outputs.



# SA.22c **Precision Rubidium Oscillator**

### **Mechanical Specifications**





SCALE 1:2 TOLERANCES: .XX ±.01 .XXX ±.005

#### **J1 Connector Pinout**

Pin Number	Function	Pin Number	Function
1	GND	10	GND
2	+15 VDC PWR-IN	11	GND
3	GND	12	SERVICE
4	+15 VDC PWR-IN	13	DATA IN
5	FREQ CNTRL	14	LOCK
6	+5 VDC PWR-IN	15	1PPS IN
7	1PPS OUT	16	DATA OUT
8	GND	17	NC
9	RF OUT-ACMOS	18	NC



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